TPS22946 Ultralow Power, Low Input Voltage, Current-Limited Load Switch With Shutoff, Auto-Restart, and Overcurrent Condition Time-Out

1 Features

- Ultralow Quiescent Current 1 μA (Typical) at $V_{IN} = 1.8$ V
- Input Voltage Range: 1.62 V to 5.5 V
- Low ON-Resistance
  - $r_{ON} = 300$ mΩ at $V_{IN} = 5.5$ V
  - $r_{ON} = 400$ mΩ at $V_{IN} = 3.3$ V
  - $r_{ON} = 500$ mΩ at $V_{IN} = 2.5$ V
  - $r_{ON} = 600$ mΩ at $V_{IN} = 1.8$ V
- Selectable Minimum Current Limit: 155 mA, 70 mA, or 30 mA
- Integrated Inrush Current Time-out (8 ms)
- Shutdown Current: < 1 μA
- Thermal Shutdown
- Fault Blanking
- Auto Restart
- Overcurrent Condition Time-out (Automatic Disable for Permanent Overcurrent)
- 1.8-V Compatible Control Input
- ESD Performance Tested Per JESD 22
  - 6000-V Human-Body Model (A114-B, Class II)
- Tiny DSBGA Package 1.4 mm × 0.9 mm (YZP)

2 Applications

- Fingerprint Module Protection
- Portable Consumer Electronics
- Mobile Phones
- Smartphones
- Notebooks
- GPS Devices

3 Description

The TPS22946 is an ultralow power load switch that provides protection to systems and loads in high-current conditions. The device contains a 300-mΩ current-limited P-channel MOSFET that can operate over an input voltage range of 1.62 V to 5.5 V. The switch is controlled by an on/off input (ON), which can interface directly with low-voltage control signals. The TPS22946 includes thermal shutdown protection that prevents damage to the device when a continuous over-current condition causes excessive heating by turning off the switch.

When the switch current reaches the maximum limit, the TPS22946 operates in a constant-current mode to prohibit excessive currents from causing damage. The current limit can be selected using the CL input: a high CL input sets the current limit to 155 mA, a low CL input sets the current limit to 70 mA, and a floating CL input sets the current limit to 30 mA.

If the constant current condition persists after 10 ms, the switch is turned off and the fault signal pin (OC) is pulled low. The TPS22946 has an auto-restart feature which turns the switch on again after 70 ms if the ON pin is still active. If the TPS22946 remains in an overcurrent condition for 5 seconds, the device shuts off until it is turned on again by setting the ON control signal off and then on.

If the device is used to protect an LDO, the inrush current required by the LDO at startup can, in some cases, exceed the current limit and initiate a blanking (current limiting) condition. The TPS22946 provides allowance for this scenario during startup of the LDO by temporarily increasing the current limit to 435 mA for 8 ms after the load switch is enabled.

The TPS22946 is available in space-saving 6-pin DSBGA (YZP) package. The device is characterized for operation over the free-air temperature range of −40°C to 85°C.

Device Information

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPS22946</td>
<td>DSBGA (6)</td>
<td>0.90 mm × 1.40 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Typical Application Schematic
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## 4 Revision History

Changes from Revision A (February 2010) to Revision B

- Added Pin Configuration and Functions section, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section ............................. 1
5 Pin Configuration and Functions

6-Pin DSBGA YZP Package

Pin Assignments

<table>
<thead>
<tr>
<th>A1</th>
<th>B1</th>
<th>C1</th>
<th>C2</th>
</tr>
</thead>
<tbody>
<tr>
<td>OC</td>
<td>GND</td>
<td>ON</td>
<td>ON</td>
</tr>
</tbody>
</table>

Pin Functions

<table>
<thead>
<tr>
<th>PIN NO.</th>
<th>NAME</th>
<th>I/O</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>A1</td>
<td>V_OUT</td>
<td>O</td>
<td>Output of the power switch</td>
</tr>
<tr>
<td>A2</td>
<td>V_IN</td>
<td>I</td>
<td>Supply. Input to the power switch and the supply voltage for the device</td>
</tr>
<tr>
<td>B1</td>
<td>GND</td>
<td>–</td>
<td>Ground</td>
</tr>
<tr>
<td>B2</td>
<td>CL</td>
<td>I</td>
<td>Current limit selection. CL high is 155-mA current limit, CL low is 70-mA current limit, and CL floating is 30-mA current limit.</td>
</tr>
<tr>
<td>C1</td>
<td>OC</td>
<td>O</td>
<td>Overcurrent output flag. Active-low open-drain output that indicates an overcurrent, supply undervoltage, or overtemperature state.</td>
</tr>
<tr>
<td>C2</td>
<td>ON</td>
<td>I</td>
<td>On/off control input</td>
</tr>
</tbody>
</table>
6 Specifications

6.1 Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_{IN}, V_{OUT}, ON, CL</td>
<td>–0.3</td>
<td>6</td>
</tr>
<tr>
<td>T_J</td>
<td>–40</td>
<td>125</td>
</tr>
<tr>
<td>T_{stg}</td>
<td>–65</td>
<td>150</td>
</tr>
</tbody>
</table>

6.2 ESD Ratings

<table>
<thead>
<tr>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>±6000</td>
<td>V</td>
</tr>
</tbody>
</table>

6.3 Recommended Operating Conditions

<table>
<thead>
<tr>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_{IN}</td>
<td>1.62</td>
<td>5.5</td>
</tr>
<tr>
<td>V_{ON}</td>
<td>0</td>
<td>5.5</td>
</tr>
<tr>
<td>V_{CL}</td>
<td>0</td>
<td>V_{IN}</td>
</tr>
<tr>
<td>V_{OUT}</td>
<td>0</td>
<td>V_{IN}</td>
</tr>
<tr>
<td>T_{A}</td>
<td>–40</td>
<td>85</td>
</tr>
<tr>
<td>t_{CLSET}</td>
<td>8</td>
<td>ms</td>
</tr>
<tr>
<td>C_{IN}</td>
<td>1 (1)</td>
<td>μF</td>
</tr>
</tbody>
</table>

6.4 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC (1)</th>
<th>TPS22946</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>R_{JA}</td>
<td>Junction-to-ambient thermal resistance</td>
<td>131</td>
</tr>
<tr>
<td>R_{JC(top)}</td>
<td>Junction-to-case (top) thermal resistance</td>
<td>1.3</td>
</tr>
<tr>
<td>R_{JB}</td>
<td>Junction-to-board thermal resistance</td>
<td>22.6</td>
</tr>
<tr>
<td>ψ_{JT}</td>
<td>Junction-to-top characterization parameter</td>
<td>5.2</td>
</tr>
<tr>
<td>ψ_{JB}</td>
<td>Junction-to-board characterization parameter</td>
<td>22.6</td>
</tr>
</tbody>
</table>

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.
### 6.5 Electrical Characteristics

$V_{IN} = 1.62 \, \text{V to} \, 5.5 \, \text{V}$, TYP values at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>$T_A$ (1)</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{IN}$ Average quiescent current</td>
<td>$I_{OUT} = 0 , mA$, $V_{IN} = 4.5 , \text{V to} , 5.5 , \text{V}$</td>
<td>Full range</td>
<td>1.5</td>
<td>5</td>
<td></td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td></td>
<td>$I_{OUT} = 0 , mA$, $V_{IN} = 3.0 , \text{V to} , 3.6 , \text{V}$</td>
<td></td>
<td>1.3</td>
<td>4</td>
<td></td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td></td>
<td>$I_{OUT} = 0 , mA$, $V_{IN} = 1.62 , \text{V to} , 1.98 , \text{V}$</td>
<td></td>
<td>1</td>
<td>3</td>
<td></td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>$I_{IN(OFF)}$ OFF state supply current</td>
<td>$V_{ON} = 0 , V$, $V_{IN} = 3.6 , \text{V}$, $V_{OUT}$ open</td>
<td>Full range</td>
<td>0.1</td>
<td>1</td>
<td></td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>$I_{OUT(LEAKAGE)}$ OFF state switch current</td>
<td>$V_{ON} = 0 , V$, $V_{IN} = 3.6 , \text{V}$, $V_{OUT}$ short to GND</td>
<td>Full range</td>
<td>0.1</td>
<td>1.1</td>
<td></td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>$r_{ON}$ ON-state resistance</td>
<td>$I_{OUT} = -100 , mA$</td>
<td>$V_{IN} = 5.5 , \text{V}$</td>
<td>Full range</td>
<td>0.3</td>
<td>0.4</td>
<td>(\Omega)</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 3.3 , \text{V}$</td>
<td>Full range</td>
<td>0.4</td>
<td>0.55</td>
<td>(\Omega)</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 2.5 , \text{V}$</td>
<td>Full range</td>
<td>0.5</td>
<td>0.8</td>
<td>(\Omega)</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 1.8 , \text{V}$</td>
<td>Full range</td>
<td>0.6</td>
<td>0.85</td>
<td>(\Omega)</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 1.62 , \text{V}$</td>
<td>Full range</td>
<td>0.7</td>
<td>0.9</td>
<td>(\Omega)</td>
</tr>
<tr>
<td>$I_{ON}$ ON input leakage current</td>
<td>$V_{ON} = V_{IN}$ or GND</td>
<td>$V_{IN} = 1.8 , \text{V}$, $V_{OUT} = 1.5 , \text{V}$, $CL = \text{GND}$</td>
<td>Full range</td>
<td>70</td>
<td>85</td>
<td>120</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 3.3 , \text{V}$, $V_{OUT} = 3.0 , \text{V}$, $CL = \text{GND}$</td>
<td>Full range</td>
<td>60</td>
<td>80</td>
<td>115</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 1.8 , \text{V}$, $V_{OUT} = 1.5 , \text{V}$, $CL = \text{VIN}$</td>
<td>Full range</td>
<td>155</td>
<td>175</td>
<td>235</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 3.3 , \text{V}$, $V_{OUT} = 3.0 , \text{V}$, $CL = \text{VIN}$</td>
<td>Full range</td>
<td>135</td>
<td>165</td>
<td>230</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 1.8 , \text{V}$, $V_{OUT} = 1.5 , \text{V}$, $CL$ floating</td>
<td>Full range</td>
<td>30</td>
<td>45</td>
<td>60</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN} = 3.3 , \text{V}$, $V_{OUT} = 3.0 , \text{V}$, $CL$ floating</td>
<td>Full range</td>
<td>28</td>
<td>40</td>
<td>60</td>
</tr>
<tr>
<td>$I_{LIMIT}$ Inrush current limit</td>
<td>$R_i = 1 , \Omega$, $V_{IN} = 3.3 , \text{V}$, $V_{OUT} = 2.3 , \text{V}$</td>
<td>Full range</td>
<td>375</td>
<td>435</td>
<td>685</td>
<td>mA</td>
</tr>
<tr>
<td>$V_{OL}$ OC output logic low voltage</td>
<td>$V_{IN} = 5 , \text{V}$, $I_{SINK} = 10 , mA$</td>
<td>Full range</td>
<td>0.1</td>
<td>0.2</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>$I_{OH}$ OC output high leakage current</td>
<td>$V_{IN} = 5 , \text{V}$, Switch ON</td>
<td>Full range</td>
<td>0.1</td>
<td>0.3</td>
<td></td>
<td>(\mu\text{A})</td>
</tr>
</tbody>
</table>

(1) Full range $T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$

(2) See Overtemperature Protection.

---

| $V_{OL}$ OC output logic low voltage | $V_{IN} = 5 \, \text{V}$, $I_{SINK} = 10 \, mA$ | Full range | 0.1 | 0.2 |     | V |
| $I_{OH}$ OC output high leakage current | $V_{IN} = 5 \, \text{V}$, Switch ON | Full range | 0.1 | 0.3 |     | \(\mu\text{A}\) |

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(1) Full range $T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$

(2) See Overtemperature Protection.
### 6.6 Switching Characteristics

$V_{IN} = 1.8 \, \text{V}$, $R_L = 50 \, \Omega$, $C_L = 1 \, \mu\text{F}$, $T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$, TYP values at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$t_{\text{PWRON}}$</td>
<td>Power-on time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$R_L = 50 , \Omega$, $C_L = 1 , \mu\text{F}$</td>
<td>192</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{PWROFF}}$</td>
<td>Power-off time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$R_L = 50 , \Omega$, $C_L = 1 , \mu\text{F}$</td>
<td>0.55</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{ON}}$</td>
<td>Turnon time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$R_L = 50 , \Omega$, $C_L = 1 , \mu\text{F}$</td>
<td>125</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{OFF}}$</td>
<td>Turnoff time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$R_L = 50 , \Omega$, $C_L = 1 , \mu\text{F}$</td>
<td>115</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_R$</td>
<td>$V_{\text{OUT}}$ rise time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$R_L = 50 , \Omega$, $C_L = 1 , \mu\text{F}$</td>
<td>35</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_f$</td>
<td>$V_{\text{OUT}}$ fall time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$R_L = 50 , \Omega$, $C_L = 1 , \mu\text{F}$</td>
<td>120</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{BLANK}}$</td>
<td>Overcurrent blanking time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>7</td>
<td>ms</td>
<td>10</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>15</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{RESTART}}$</td>
<td>Auto-restart time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>50</td>
<td>ms</td>
<td>70</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>95</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{TIMEOUT}}$</td>
<td>Overcurrent detection time-out(1)</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$V_{IN} = V_{ON} = 3.3 , \text{V}$, hard short(2)</td>
<td>6000</td>
<td>ms</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{OVRTEMP}}$</td>
<td>Overtemperature detection maximum response time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>7.7</td>
<td>ms</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{MODOC}}$</td>
<td>Moderate overcurrent detection maximum response time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$V_{IN} = V_{ON} = 1.8 , \text{V}$, Moderate over-current condition(3)</td>
<td>63.5</td>
<td>ms</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$V_{IN} = V_{ON} = 3.3 , \text{V}$, Moderate over-current condition(3)</td>
<td>65.5</td>
<td>ms</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$t_{\text{HARDSHORT}}$</td>
<td>Hard-short detection maximum response time</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$V_{IN} = V_{ON} = 1.8 , \text{V}$, hard short(2)</td>
<td>270</td>
<td>µs</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$V_{IN} = V_{ON} = 3.3 , \text{V}$, hard short(2)</td>
<td>295</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(1) See Automatic Disable in Case of Permanent Overcurrent.
(2) Hard short check is performed at the output voltage of the switch. Hard short condition is active when $V_{\text{OUT}} < 2/3 \, V_{\text{IN}}$.
(3) If the current going through the switch is above $I_{\text{LIM}}$, then the moderate over-current condition is activated.
6.7 Typical Characteristics

Figure 1. ON-Resistance vs Input Voltage

Figure 2. ON-Resistance Vs Temperature

Figure 3. Input Current (Quiescent) vs Temperature

Figure 4. Input Current (Leakage) vs Temperature

Figure 5. Input Current (Off) vs Temperature

Figure 6. Current Limit vs Temperature
Typical Characteristics (continued)

Figure 7. Current Limit vs Input Voltage

Figure 8. t_{Blank} vs Temperature

Figure 9. t_{Reset} vs Temperature

Figure 10. t_{PWRON} vs Temperature

Figure 11. t_{PWROFF} vs Temperature

Figure 12. ON Threshold
Typical Characteristics (continued)

Figure 13. $t_{ON}$ Response

Figure 14. $t_{OFF}$ Response

Figure 15. $t_{blank}$ Response

Figure 16. $t_{Restart}$ Response

Figure 17. Hard Short-Circuit Response

Figure 18. Short-Circuit Response

NOTE: $V_{in}$ signal forces the device to go into over-current mode.
Typical Characteristics (continued)

Figure 19. Moderate Overcurrent Response

- $V = V_{IN} = 3.3\, V$
- $C = 10\, \mu F$
- $C_{INT} = 1\, \mu F$
- $R = 5\, \Omega$
7 Parameter Measurement Information

![Test Circuit and t\text{ON}/t\text{OFF} Waveforms](image)

**Figure 20. Test Circuit and t\text{ON}/t\text{OFF} Waveforms**

![t\text{PWRON}/t\text{PWROFF} Waveforms](image)

**Figure 21. t\text{PWRON}/t\text{PWROFF} Waveforms**
8 Detailed Description

8.1 Overview

The TPS22946 is an ultralow power load switch that provides protection to systems and loads in high-current conditions. The device contains a 300-mΩ current-limited P-channel MOSFET that can operate over an input voltage range of 1.62 V to 5.5 V. The switch is controlled by an on/off input (ON), which is capable of interfacing directly with low-voltage control signals. The TPS22946 includes thermal shutdown protection that prevents damage to the device when a continuous over-current condition causes excessive heating by turning off the switch.

When the switch current reaches the maximum limit, the TPS22946 operates in a constant-current mode to prohibit excessive currents from causing damage. The current limit can be selected using the CL input: a high CL input sets the current limit to 155 mA, a low CL input sets the current limit to 70 mA, and a floating CL input sets the current limit to 30 mA.

If the constant current condition still persists after 10 ms, the switch is turned off and the fault signal pin (OC) is pulled low. The TPS22946 has an auto-restart feature which turns the switch on again after 70 ms if the ON pin is still active. If the TPS22946 remains in an over-current condition for 5 seconds, the device shuts off until it is turned on again by setting the ON control signal off and then on.

If the device is used to protect an LDO, the inrush current required by the LDO at startup can, in some cases, exceed the current limit and initiate a blanking (current limiting) condition. The TPS22946 device provides allowance for this scenario during startup of the LDO by temporarily increasing the current limit to 435 mA for 8 ms after the load switch is enabled.

The TPS22946 is available in a space-saving 6-pin DSBGA (YZP) package. The device is characterized for operation over the free-air temperature range of –40°C to 85°C.

<table>
<thead>
<tr>
<th>Feature</th>
<th>TPS22946</th>
</tr>
</thead>
<tbody>
<tr>
<td>f&lt;sub&gt;ON&lt;/sub&gt; (TYP) AT 5.5 V</td>
<td>300 mΩ</td>
</tr>
<tr>
<td>CURRENT LIMIT</td>
<td>30 mA, 70 mA, or 155 mA</td>
</tr>
<tr>
<td>INTEGRATED INRUSH CURRENT TIME-OUT</td>
<td>Yes</td>
</tr>
<tr>
<td>CURRENT LIMIT BLANKING TIME</td>
<td>10 ms</td>
</tr>
<tr>
<td>AUTO-RESTART TIME</td>
<td>70 ms</td>
</tr>
<tr>
<td>OVERCURRENT TIME-OUT</td>
<td>6 s</td>
</tr>
<tr>
<td>ENABLE</td>
<td>Active high</td>
</tr>
</tbody>
</table>

8.2 Functional Block Diagram
8.3 Feature Description

8.3.1 Detection Schemes

8.3.1.1 Overtemperature Detection

The thermal shutdown detection circuit is active every 8 ms for a period of 0.5 ms. The thermal shutdown protects the part from internally or externally generated excessive temperatures. During an over-temperature condition the switch is turned-off (Open). The switch automatically turns-on (closes) again if temperature of the die drops below the threshold temperature while the part is still enabled.

In addition, if an overcurrent fault condition is detected due to a moderate overcurrent or a hard-short, the thermal shutdown is activated immediately and stays on continuously for the duration of blanking (see Figure 32).

![Diagram of Overtemperature Detection](image)

NOTE: Case where the temperature causes the overtemperature detection circuit to trip before the other detection schemes.

**Figure 22. Overtemperature Detection**
Feature Description (continued)

8.3.1.2 Hard-Short Detection

The hard-short detection circuit is active every 250 µs for a period of 125 µs. A comparator monitors the output voltage, $V_{OUT}$. A hard short is detected when $V_{OUT}$ is lower than $2/3 V_{IN}$. The switch then goes into current-limiting mode.

![Diagram showing hard short detection and current limiting](image)

---

Figure 23. Hard-Short Detection
Feature Description (continued)

8.3.1.3 Moderate Overcurrent Detection

The moderate overcurrent detection circuit is active every 64 ms for a period of 0.5 ms. A moderate over-current condition is triggered when the output current of the switch exceeds the current limit value and is not yet into hard short condition. The switch then goes into current-limiting mode.

![Diagram of overcurrent detection circuit]

NOTE: The overcurrent does not cause the temperature to go above 140°C here.

Figure 24. Moderate Overcurrent Detection
Feature Description (continued)

8.3.1.4 Current Limiting Mode

When an overcurrent condition (moderate or a hard short) is detected, the TPS22946 operates in a constant-current mode to prohibit excessive currents from causing damage. TPS22946 has a current limit of 30 mA, 70 mA, or 155 mA.

If the constant current condition still persists after 10ms, the device shuts off the switch and pulls the fault signal pin (OC) low. The TPS22946 has an auto-restart feature which turns the switch on again after 70 ms if the ON pin is still active.

8.3.1.5 Fault Reporting

When a moderate overcurrent, hard short or overtemperature condition is detected, OC is set active low to signal a fault condition. OC is an open-drain MOSFET and requires a pullup resistor between \( V_{IN} \) and OC. During shutdown, the pulldown on OC is disabled, reducing current draw from the supply.

8.3.1.6 Power-On and Power-Off Sequence

The device is enabled internally only once the hard-short detection circuit is enabled.
Feature Description (continued)

Current Limit Threshold

- **V\text{IN}**
- **0V**
- **V\text{ON}**
- **0V**
- **V\text{OUT}**

- **V\text{IN}/2**
- **V\text{ON}** is tied directly to **V\text{IN}**

- **t\text{PWRON}**

- **LDO Output stable**

- **t\text{CLSET}**

- **8 ms**

- **Value on the CL pin should be stable by this edge for **t\text{CLSET}**

- **Changes on CL pin, will not affect current limit threshold after this time**

Moderate Over Current Detection

- **8 ms**

Over Temperature Detection

- **8 ms**

Hard Short Detection

- **0.125ms**

Load Switch Status

- **SWITCH OPEN**
- **SWITCH CLOSE**

**Figure 25. Power-On/Power-Off Sequence Timing**
Feature Description (continued)

8.3.1.7 Automatic Disable in Case of Permanent Overcurrent

When the switch enters the current-limiting mode due to a hard short condition or a moderate over-current condition, TPS22946 goes through the 10-ms blanking state and the 70-ms auto restart state. If the hard-short condition or the moderate over-current condition persists after 5 s, the part shuts off regardless of the ON signal. The switch is turned on again after a power reset if the ON pin is HIGH.

8.3.2 Inrush Current Time-out Feature

The inrush current required by the LDO at startup can in some cases exceed the current limit and initiate a blanking (current limiting) condition. TPS22946 provides allowance for this scenario by temporarily increasing the current limit to 435 mA for 8 ms after the load switch is enabled. This time-out is initiated by the positive edge transition on the ON signal.

Figure 26. Inrush Current Time-out Circuit
8.3.3 CL Control Pin

The TPS22946 supports three current limits: 30 mA, 70 mA, and 155 mA. The current limit selection is determined by the status of the digital input CL pin, as shown in Table 2. A high impedance, or floating, condition allows the CL pin to support a third state. The TPS22946 monitors the state of the CL pin during start-up from a disabled state, and upon start-up sets the current limit accordingly. When floating the CL pin, keep the total capacitance on the pin less than 100 pF and the resistive loading greater than 10 MΩ to ensure proper operation. Any changes to the state of the CL pin after the start-up operation has completed are ignored until the next start-up cycle.

The CL pin must be driven with logic levels referenced to VIN. The CL pin can be tied high or low on the printed wiring board (PWB) or driven by a general purpose I/O (GPIO), as long as the \( V_{IL} \) and \( V_{IH} \) recommended operating conditions are met.

<table>
<thead>
<tr>
<th>CL PIN STATUS</th>
<th>CURRENT LIMIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Logic low(^{(1)})</td>
<td>70 mA</td>
</tr>
<tr>
<td>Float(^{(2)})</td>
<td>30 mA</td>
</tr>
<tr>
<td>Logic high(^{(1)})</td>
<td>155 mA</td>
</tr>
</tbody>
</table>

\(^{(1)}\) Resistance to VCC or GND < 100 Ω
\(^{(2)}\) Load on CL: C < 100 pF, R > 10 MΩ
8.3.4 Overtemperature Protection

An overtemperature condition occurs when the temperature of the part is greater than 140°C. The OC flag will go low to indicate a fault. If the overtemperature condition persists for more than 6 seconds, the part times out and shuts OFF. The part must be enabled by either toggling the ON pin or the VIN pin. If the temperature falls below 130°C within 5 seconds, the part will start normal operation.

If the temperature is not constantly high above 140°C and is toggling between greater than 140°C and less than 130°C, the internal time-out timer keeps resetting. If this event occurs more than 32 times, it will cause the part to shut OFF. It can be enabled by toggling either the ON pin or the VIN pin.
8.4 Device Functional Modes

Table 3. Function Table

<table>
<thead>
<tr>
<th>ON</th>
<th>CL</th>
<th>TPS22946</th>
</tr>
</thead>
<tbody>
<tr>
<td>L</td>
<td>x</td>
<td>( V_{IN} ) to ( V_{OUT} ) switch is off (open)</td>
</tr>
<tr>
<td>H</td>
<td>x</td>
<td>( V_{IN} ) to ( V_{OUT} ) switch is on (closed)</td>
</tr>
<tr>
<td>x</td>
<td>( H^{(1)} )</td>
<td>Current limit set to 155 mA</td>
</tr>
<tr>
<td>x</td>
<td>( L^{(1)} )</td>
<td>Current limit set to 70 mA</td>
</tr>
<tr>
<td>x</td>
<td>Float(^{(2)})</td>
<td>Current limit set to 30 mA</td>
</tr>
</tbody>
</table>

(1) Resistance to VCC or GND < 100 \( \Omega \)
(2) Load on CL: \( C < 100 \) pF, \( R > 10 \) M\( \Omega \)

Figure 30. Functional Flow Diagram
Figure 31. Moderate Overcurrent Detection Flow Diagram
Figure 32. Overtemperature Detection Flow Diagram
Figure 33. Hard Short-Circuit Detection Flow Diagram
9 Application and Implementation

NOTE
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 On/Off Control
The ON pin controls the state of the switch. Activating ON continuously holds the switch in the on state so long as there is no fault. A junction temperature in excess of 150°C overrides the ON control to turn off the switch. ON is active HIGH and has a low threshold making it capable of interfacing with low voltage signals. When the MOSFET is off, the body diode is disabled so no current can flow through it from the input to the output; however, the body diode does not prevent reverse current flowing.

9.2 Typical Application
This application demonstrates how the TPS22946 can be used to power a downstream load that includes a capacitive element (C\textsubscript{LOAD}).

![Typical Application Schematic](image)

Figure 34. Typical Application Schematic

9.2.1 Design Requirements
For this design example, use the following as the input parameters.

<table>
<thead>
<tr>
<th>DESIGN PARAMETER</th>
<th>EXAMPLE VALUE</th>
</tr>
</thead>
<tbody>
<tr>
<td>V\textsubscript{IN}</td>
<td>3.3 V</td>
</tr>
<tr>
<td>Output capacitance (C\textsubscript{LOAD})</td>
<td>1 (\mu)F</td>
</tr>
<tr>
<td>V\textsubscript{OUT} rise time ((t\textsubscript{R}))</td>
<td>50 (\mu)s</td>
</tr>
</tbody>
</table>
9.2.2 Detailed Design Procedure
To begin the design process, the designer must know the following:
- \( V_{\text{IN}} \) voltage
- Output capacitance (\( C_{\text{LOAD}} \))
- \( V_{\text{OUT}} \) rise time (\( t_R \))

The TPS22946 has a 435-mA current limit during initial turnon of the switch, \( I_{\text{limit,inrush}} \). This current limit is higher than the steady-state current limit, \( I_{\text{LIM}} \). The purpose of this feature is to allow the inrush current that is caused by charging up the capacitor, \( C_{\text{LOAD}} \). To calculate the inrush current that is caused by the capacitor during initial turnon, use the following equation:

\[
I_{\text{INRUSH}} = C_L \times \frac{dV_{\text{OUT}}}{dt}
\]

where
- \( I_{\text{INRUSH}} \) = amount of inrush current caused by \( C_{\text{LOAD}} \)
- \( C_L \) = capacitance on \( V_{\text{OUT}} \)
- \( dt \) = \( V_{\text{OUT}} \) rise time
- \( dV_{\text{OUT}} \) = increase in \( V_{\text{OUT}} \) during the rise time

Using the given example values, the inrush current in this typical application will be 66-mA:

\[
66 \text{ mA} = 1 \mu\text{F} \times 3.3 \text{ V} / 50 \mu\text{F}
\]

The oscilloscope capture in Figure 35 shows the inrush current for the given design example.

9.2.3 Application Curve

Figure 35. Inrush Current With 1-\( \mu \)F Output Capacitor
10 Power Supply Recommendations

The device is designed to operate from a VIN range of 1.62 to 5.5 V. The VIN power supply should be well regulated and placed as close to the VIN terminal as possible. The power supply must be able to withstand all transient load current steps. In most situations, using the minimum recommended input capacitance of 1 uF is sufficient to prevent the supply voltage from dipping when the switch is turned on. In cases where the power supply is slow to respond to a large transient current or large load current step, additional bulk capacitance may be required on the input.

11 Layout

11.1 Layout Guidelines

- The C\text{IN} capacitor should be placed as close as possible to the V_{\text{IN}} pin.
- The V_{\text{IN}} and V_{\text{OUT}} traces should be the appropriate width to carry the load current.
- The CL pin may be connected directly the GND or VIN (depending on the desired current limit). The CL pin may also be left floating.

11.2 Layout Example

![Layout Example Diagram]

Figure 36. Layout Example
12 Device and Documentation Support

12.1 Trademarks
All trademarks are the property of their respective owners.

12.2 Electrostatic Discharge Caution
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.3 Glossary
SLYZ022 — Ti Glossary.
This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
## PACKAGE INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status (1)</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan (2)</th>
<th>Lead/Ball Finish (6)</th>
<th>MSL Peak Temp (3)</th>
<th>Op Temp (°C)</th>
<th>Device Marking (4/5)</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPS22946YZPR</td>
<td>ACTIVE</td>
<td>DSBGA</td>
<td>YZP</td>
<td>6</td>
<td>3000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>SNAGCU</td>
<td>Level-1-260C-UNLIM</td>
<td>-40 to 85</td>
<td>(SH ~ SH2)</td>
<td></td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
- ** OBSOLETE**: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check [http://www.ti.com/productcontent](http://www.ti.com/productcontent) for the latest availability information and additional product content details.

- **TBD**: The Pb-Free/Green conversion plan has not been defined.
- **Pb-Free (RoHS)**: TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
- **Pb-Free (RoHS Exempt)**: This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
- **Green (RoHS & no Sb/Br)**: TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

*All dimensions are nominal*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0 (mm)</th>
<th>B0 (mm)</th>
<th>K0 (mm)</th>
<th>P1 (mm)</th>
<th>W (mm)</th>
<th>Pin1 Quadrant</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPS22946YZPR</td>
<td>DSBGA</td>
<td>YZP</td>
<td>6</td>
<td>3000</td>
<td>178.0</td>
<td>9.2</td>
<td>1.02</td>
<td>1.52</td>
<td>0.63</td>
<td>4.0</td>
<td>8.0</td>
<td>Q1</td>
</tr>
</tbody>
</table>

**TAPE DIMENSIONS**

- **A0**: Dimension designed to accommodate the component width
- **B0**: Dimension designed to accommodate the component length
- **K0**: Dimension designed to accommodate the component thickness
- **W**: Overall width of the carrier tape
- **P1**: Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

- **Q1**: Upper left quadrant
- **Q2**: Upper right quadrant
- **Q3**: Lower right quadrant
- **Q4**: Lower left quadrant
### TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
<th>Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TPS22946YZPR</td>
<td>DSBGA</td>
<td>YZP</td>
<td>6</td>
<td>3000</td>
<td>220.0</td>
<td>220.0</td>
<td>35.0</td>
</tr>
</tbody>
</table>
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parentheses are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 (www.ti.com/lit/sbva017).
5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.
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